

Full speed ahead!

FAST CURING SMP ADHESIVE



DUAL SMP 400P®





The Dual SMP system is a smart choice for a more efficient production process.

With a re-designed gear transmission and an optimized static mixer, Bostik introduces its new Dual SMP gun.

Combining an advanced adhesive (A-component) with an accelerator (B-component), the easy to use, patented, Dual SMP gun from Bostik mixes both components consistently and uniformly resulting in extreme green strength and faster curing times. This, in turn, reduces finishing times in a variety of replacement and production processes.



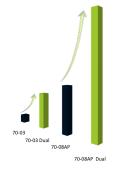
The B-component ensures a complete cure of the adhesive bead regardless of dimensions or environmental conditions such as heat and humidity. This makes the Dual SMP system ideal for use in dry conditions.

BEAD CROSS-SECTION



Bostik's Dual SMP system accelerates curing time and improves the green strength of adhesives and sealants in the initial hours following application.

HIGH GREEN STRENGTH OF DUAL SMP



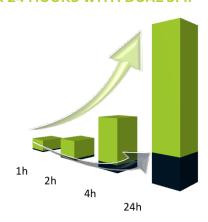
Direct green strength



Curing behavior Single component SMP (blue) v Dual SMP (green)

Dual SMP is a reliable and uncompromising two component system offering 7 times faster strength build up compared to single component systems. Developed for use in transportation and the automotive aftermarket, the Dual SMP system offers many advantages in terms of performance, efficiency and cost-inuse benefits.

75% OF FINAL SHEAR STRENGTH REACHED AFTER 24 HOURS WITH DUAL SMP



Strength build upSingle component SMP (blue) v Dual SMP (green)

CASE STUDY

In recent field trials, a European bus manufacturer found it was able to significantly reduce processing and finishing times as a result of the high green strength achieved with the Dual SMP system. The process improvements included a reduction in clamping times from 4 hours to 30 minutes.

MARKETS

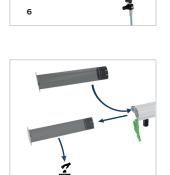


QUICK USER INSTRUCTIONS

























Smart help: www.bostik.com

